

VERSION WITH MARKINGS TO SHOW CHANGES MADETITLE:

Specification at page 1, line 1:

~~MULTILAYER CERAMIC SUBSTRATE AND METHOD FOR
FABRICATING THE SAME~~ METHOD FOR FABRICATING A MULTILAYER
CERAMIC SUBSTRATE

SPECIFICATION:

Specification at page 1, line 5:

CROSS-RELATED APPLICATIONS

This application is a Divisional application of U.S. Patent Application
Serial No. 09/173,288, filed October 14, 1998.

CLAIMS:

1 3. (As Amended) ~~The method for fabricating a multilayer ceramic substrate
recited in claim 1,~~ A method for fabricating a multilayer ceramic substrate
comprising the steps of:

4 (a) manufacturing an intaglio plate of flexible resin substance, on which a
5 first groove corresponding to a first conductive pattern is formed and a second
6 groove having a depth deeper than that of the first groove is formed at a place
7 corresponding to a via of the first conductive pattern;

8 (b) filling the first and the second grooves with an electroconductive paste;

9 (c) increasing conductivity of respective paths in said first and second
10 grooves by deaerating and drying the paste;

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11 (d) adding additional electroconductive paste to said first and second
12 grooves to replenish a decremented volume of said paste ;

13 (e) gluing said intaglio plate onto a ceramic substrate by applying heat and
14 pressure;

15 (f) separating said intaglio plate from said ceramic substrate to have a
16 pattern of the electroconductive paste transferred onto the ceramic substrate, and
17 burning it so as to form said first conductive pattern on the ceramic substrate;

18 (g) forming an insulation layer on said first conductive pattern, wherein said
19 insulation layer is formed by a printing technology covering the whole area of said
20 first conductive pattern, and is dried, said via is exposed through abrasion or
21 grinding of the dried skin of said insulation layer before burning and said insulation
22 layer is burned after the exposure of said via;

(h) forming a second conductive pattern on said insulation layer.

Claims 1, 2, and 4-21 have been cancelled.

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